Vishay Siliconix

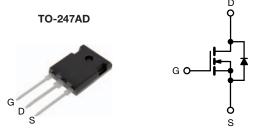
COMPLIANT

HALOGEN

FREE

E Series Power MOSFET

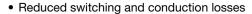
PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
$R_{DS(on)}$ max. (Ω) at 25 °C	$V_{GS} = 10 \text{ V}$	0.099			
Q _g max. (nC)	150				
Q _{gs} (nC)	24				
Q _{gd} (nC)	42				
Configuration	Single				



N-Channel MOSFET

FEATURES

- Low figure-of-merit (FOM): Ron x Qa
- Low input capacitance (Ciss)



- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	TO-247AD
Lead (Pb)-free and Halogen-free	SiHW33N60E-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-Source Voltage			V _{DS}	600	V		
Gate-Source Voltage			V_{GS}	± 30	1 v		
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	I _D	33			
		T _C = 100 °C		21	Α		
Pulsed Drain Current ^a			I _{DM}	88			
Linear Derating Factor				2.2	W/°C		
Single Pulse Avalanche Energy b			E _{AS}	793	mJ		
Maximum Power Dissipation			P_{D}	278	W		
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C		
Drain-Source Voltage Slope	$V_{DS} = 0 \text{ V to } 80 \% V_{DS}$		d\//d+	70	V/ns		
Reverse Diode dV/dt ^d		dV/dt	12	V/IIS			
Soldering Recommendations (Peak temperature) c	for 10 s			300	°C		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 7.5 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.45	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS			MAX.	UNIT
Static					•		
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	600	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} :	V _{DS} = V _{GS} , I _D = 250 μA			4.0	V
Octo Correct Lockson		$V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Gate-Source Leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$		-	± 1	μA
Zana Oata Valta aa Dusin Oannant		V _{DS} :	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 ^{\circ}\text{C}$		-	1	μΑ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \			-	10	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 16.5 A	-	0.083	0.099	Ω
Forward Transconductance a	9 _{fs}	V _{DS} = 30 V, I _D = 16.5 A		-	11	-	S
Dynamic					•		
Input Capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ $f = 1 \text{ MHz}$		-	3508	-	pF
Output Capacitance	C _{oss}			-	156	-	
Reverse Transfer Capacitance	C _{rss}			-	6	-	
Effective Output Capacitance, Energy Related ^b	C _{o(er)}	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V to } 480 \text{ V}$		-	136	-	
Effective Output Capacitance, Time Related c	C _{o(tr)}			-	468	-	
Total Gate Charge	Q _q			-	100	150	
Gate-Source Charge	Q _{qs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 16.5 \text{ A}, V_{DS} = 480 \text{ V}$		24	-	nC
Gate-Drain Charge	Q _{gd}				42	-	
Turn-On Delay Time	t _{d(on)}			-	28	56	
Rise Time	t _r	$V_{DD} = 480 \text{ V}, I_{D} = 16.5 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		-	60	90	ns
Turn-Off Delay Time	t _{d(off)}			-	99	150	
Fall Time	t _f			-	54	80	
Gate Input Resistance	R_{g}	f = 1 MHz, open drain		0.2	0.7	1.0	Ω
Drain-Source Body Diode Characteristic	s				•		
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	33	
Pulsed Diode Forward Current	I _{SM}			-	-	88	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 16.5 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C, } I_F = I_S,$ $dI/dt = 100 \text{ A/}\mu\text{s, } V_R = 20 \text{ V}$		-	503	1006	ns
Reverse Recovery Charge	Q _{rr}			-	8.5	17	μC
Reverse Recovery Current	I _{RRM}			-	26	-	A

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . c. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

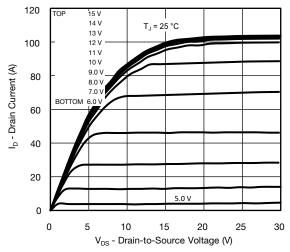


Fig. 1 - Typical Output Characteristics

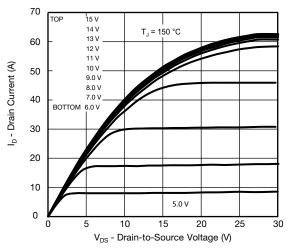


Fig. 2 - Typical Output Characteristics

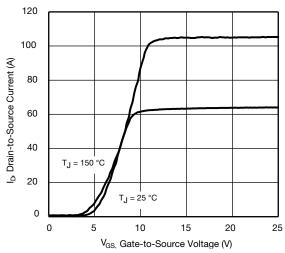


Fig. 3 - Typical Transfer Characteristics

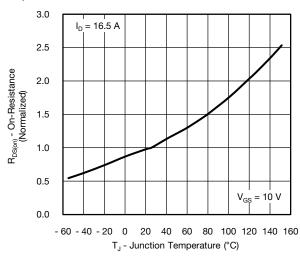


Fig. 4 - Normalized On-Resistance vs. Temperature

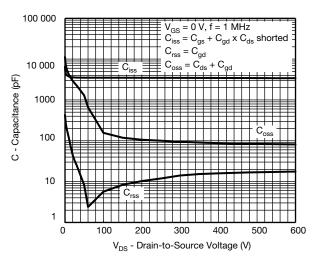


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

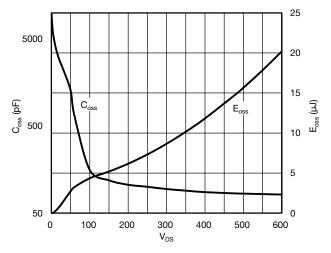


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}



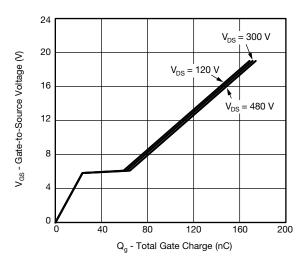


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

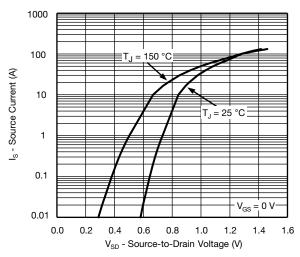


Fig. 8 - Typical Source-Drain Diode Forward Voltage

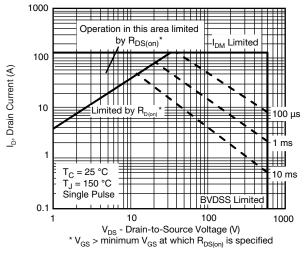


Fig. 9 - Maximum Safe Operating Area

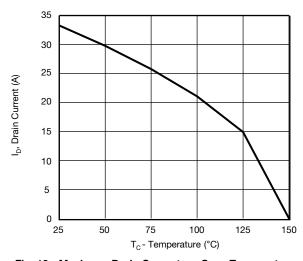


Fig. 10 - Maximum Drain Current vs. Case Temperature

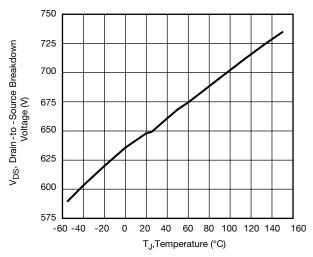


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



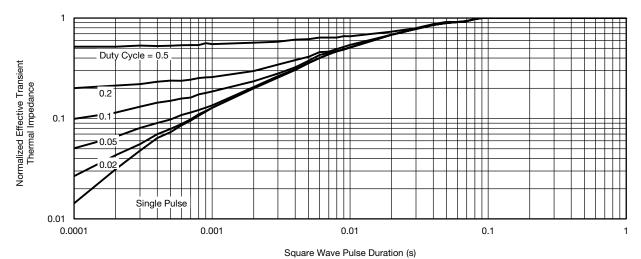


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

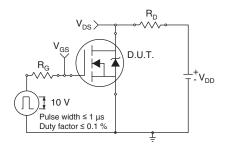


Fig. 13 - Switching Time Test Circuit

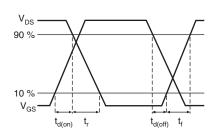


Fig. 14 - Switching Time Waveforms

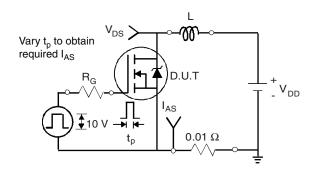


Fig. 15 - Unclamped Inductive Test Circuit

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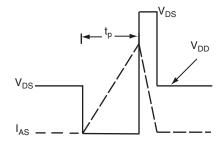


Fig. 16 - Unclamped Inductive Waveforms

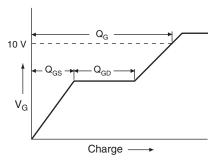


Fig. 17 - Basic Gate Charge Waveform

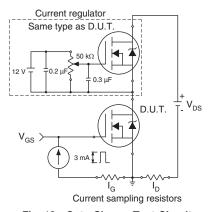
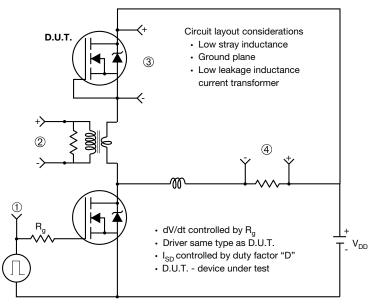


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



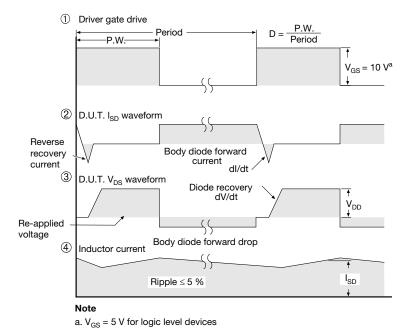
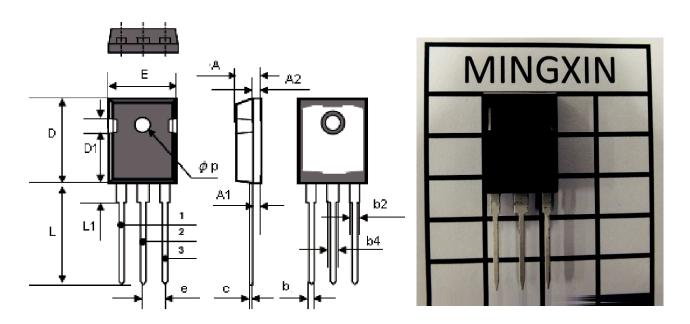


Fig. 19 - For N-Channel

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Vishay Siliconix

TO-247AD (HIGH VOLTAGE)



MILLIMETERS INCHES DIM. MIN. MAX. MIN. MAX. 5.10 0.193 0.200 4.90 A1 2.30 2.40 0.090 0.094 A2 1.92 2.08 0.076 0.082 b 1.15 1.25 0.045 0.049 b2 1.95 2.05 0.077 0.081 b4 2.85 3.11 0.112 0.122 0.6 BSC 0.024 BSC С D 20.80 21.46 0.819 0.845 D1 4.37 4.63 0.172 0.182 5.32 5.58 0.209 0.220 е Ε 15.77 16.03 0.621 0.631 19.85 20.11 0.781 0.792 L1 4.07 4.33 0.160 0.170 3.66 0.140 0.144 3.56

ECN: X12-0191-Rev. A, 22-Oct-12

DWG: 6010



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